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(54) **SEMICONDUCTOR PACKAGE AND
METHOD OF MANUFACTURING THE
SEMICONDUCTOR PACKAGE**

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ABSTRACT

A semiconductor package includes a first redistribution wiring layer having a first region and a second region surrounding the first region, a semiconductor chip disposed on the first region of the first redistribution wiring layer, a sealing member covering the semiconductor chip on the first redistribution wiring layer, vertical conductive wires penetrating the sealing member on the second region of the first redistribution wiring layer, a second redistribution wiring layer disposed on the sealing member and including second redistribution wirings electrically connected to the vertical conductive wires, and bonding pads provided on an upper surface of the first redistribution wiring layer or a lower surface of the second redistribution wiring layer, each bonding pad having a concavo-convex pattern on an upper surface of the bonding pad. The vertical conductive wires are bonded to the concavo-convex patterns of the bonding pads, respectively.

